



UNITED STATES PATENT AND TRADEMARK OFFICE

UNITED STATES DEPARTMENT OF COMMERCE
United States Patent and Trademark Office
Address: COMMISSIONER FOR PATENTS
P.O. Box 1450
Alexandria, Virginia 22313-1450
www.uspto.gov

APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/615,067	07/09/2003	Toshifumi Kojima	040894-5940	7994
9629	7590	03/13/2006	EXAMINER	
MORGAN LEWIS & BOCKIUS LLP 1111 PENNSYLVANIA AVENUE NW WASHINGTON, DC 20004			LAM, CATHY FONG FONG	
			ART UNIT	PAPER NUMBER
			1775	

DATE MAILED: 03/13/2006

Please find below and/or attached an Office communication concerning this application or proceeding.

Office Action Summary

Application No.

10/615,067

Applicant(s)

KOJIMA ET AL.

Examiner

Cathy Lam

Art Unit

1775

-- The MAILING DATE of this communication appears on the cover sheet with the correspondence address --

Period for Reply

A SHORTENED STATUTORY PERIOD FOR REPLY IS SET TO EXPIRE 3 MONTH(S) OR THIRTY (30) DAYS, WHICHEVER IS LONGER, FROM THE MAILING DATE OF THIS COMMUNICATION.

- Extensions of time may be available under the provisions of 37 CFR 1.136(a). In no event, however, may a reply be timely filed after SIX (6) MONTHS from the mailing date of this communication.
- If NO period for reply is specified above, the maximum statutory period will apply and will expire SIX (6) MONTHS from the mailing date of this communication.
- Failure to reply within the set or extended period for reply will, by statute, cause the application to become ABANDONED (35 U.S.C. § 133). Any reply received by the Office later than three months after the mailing date of this communication, even if timely filed, may reduce any earned patent term adjustment. See 37 CFR 1.704(b).

Status

- 1) ☒ Responsive to communication(s) filed on 17 January 2006.
- 2a) ☒ This action is **FINAL**. 2b) ☐ This action is non-final.
- 3) ☐ Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under *Ex parte Quayle*, 1935 C.D. 11, 453 O.G. 213.

Disposition of Claims

- 4) ☒ Claim(s) 5-7 and 10-17 is/are pending in the application.
- 4a) Of the above claim(s) _____ is/are withdrawn from consideration.
- 5) ☐ Claim(s) _____ is/are allowed.
- 6) ☒ Claim(s) 5-7 and 10-17 is/are rejected.
- 7) ☐ Claim(s) _____ is/are objected to.
- 8) ☐ Claim(s) _____ are subject to restriction and/or election requirement.

Application Papers

- 9) ☐ The specification is objected to by the Examiner.
- 10) ☒ The drawing(s) filed on 21 January 2003 is/are: a) ☐ accepted or b) ☐ objected to by the Examiner.
- Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).
- Replacement drawing sheet(s) including the correction is required if the drawing(s) is objected to. See 37 CFR 1.121(d).
- 11) ☐ The oath or declaration is objected to by the Examiner. Note the attached Office Action or form PTO-152.

Priority under 35 U.S.C. § 119

- 12) ☒ Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f).
- a) ☒ All b) ☐ Some * c) ☐ None of:
1. ☒ Certified copies of the priority documents have been received.
2. ☐ Certified copies of the priority documents have been received in Application No. _____.
3. ☐ Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)).
- * See the attached detailed Office action for a list of the certified copies not received.

Attachment(s)

- 1) ☒ Notice of References Cited (PTO-892)
- 2) ☐ Notice of Draftsperson's Patent Drawing Review (PTO-948)
- 3) ☐ Information Disclosure Statement(s) (PTO-1449 or PTO/SB/08)
Paper No(s)/Mail Date _____.
- 4) ☐ Interview Summary (PTO-413)
Paper No(s)/Mail Date. _____.
- 5) ☐ Notice of Informal Patent Application (PTO-152)
- 6) ☐ Other: _____.

In view of the amendment filed on January 17th 2006, the pending claims continue to be unpatentable as following:

Claim Objections

1. Claim 11 is objected to because of the following informalities: the term "hologenated" is believed as an error, applicant needs to check the correct spelling. Appropriate correction is required.

Claim Rejections - 35 USC § 103

1. Claims 5-7 and 10-17 are rejected under 35 U.S.C. 103(a) as being unpatentable over Ishikawa et al (US 5243142) in view of Nakatani et al (US 6108903) further in view of Kambe et al (US 6323439).

Ishikawa discloses a printed wiring board comprised of an insulating substrate (1), via hole (3), electroconductive plating (4), a filling material and a second plating layer (6) (Figs. 2 & 3).

Via hole (3) is formed through the thickness of the insulating substrate and an electroconductive plating layer (4) is plated on the wall of the via hole (3) (col 1 L 66-68). The via hole is then filled with a non-electroconductive resin paste. A second plating layer is plated over both surfaces of the cured resin paste (col 2 L 1-6). The second plating layer (6) is a conductive layer (col 3 L 52-55).

Ishikawa further teaches that the invention can be applied to a multilayer printed circuit board (col 4 L 35-37).

Ishikawa does not go into details about the ingredients of the non-conductive paste layer nor does it teach the diameter of via hole.

Art Unit: 1775

Nakatani teaches a conductive paste which is used in a connecting member that couples with circuit substrates. The conductive paste is comprised of conductive fillers, a thermosetting resin, a curing agent (or hardener) and a curing catalyst.

The conductive paste is used to fill the through holes of the connector member, the through holes have a diameter from 50 μm to 1 mm, more preferably from 100 μm to 300 μm (col 7 L 38-41). The conductive fillers have an average particles size range from 0.2 to 20 μm (col 9 L 34-35). The fillers are dispersed in the thermosetting resin which is a solvent free epoxy resin liquid (col 9 L 59-63).

The hardener used in the conductive paste can be dicyandiamide and an urea hardener such as 3-(3,4-dichlorophenyl)-1,1-dimethyl urea (col 10 L 19-22). Nakatani further teaches that the hardener is in the form of powder (col 10 L 27-28).

Nakatani teaches all the ingredients for the conductive paste, but is silent about the hardener's (or curing agent) particle size.

In view of Nakatani's teaching, the examiner is taking the position that one of ordinary skill in the art would choose a size range that is most optimum to his invention because such discovery involves only routine experimentations.

Regarding to the structure of the present invention, Kambe teaches a multilayer printed wiring board comprised of a surface wiring board and a core wiring board (Fig. 3F).

The surface wiring board is comprised of an insulating layer with through holes and conductive pattern layer (71). The conductive pattern layer is formed onto the surface of the insulating layer and on the wall of the through holes (63).

The surface wiring board is placed over the core wiring board that has plated via holes connect to the conductive pattern layer (71) in the surface wiring board (Fig. 1). The via holes (H4) in the core wiring board has a diameter of 50 μm (col 7 L 60-61).

In view of the prior art teachings, one skill in the art would fabricate a multilayer printed circuit board that has a plated through holes filled with a conductive paste or a non-conductive paste filled, and having a second conductive layer over the filled via hole for connecting to another wiring board because such structure is well known in the circuit board field. Furthermore, the conductive paste with the claimed ingredients are well known in the conductive composition art.

Conclusion

2. The prior art made of record and not relied upon is considered pertinent to applicant's disclosure. Omoya et al USP 6,139,777 and Kawakita et al USP 5,652,042 also disclose a conductive plug that has the claimed ingredients.
3. Applicant's amendment necessitated the new ground(s) of rejection presented in this Office action. Accordingly, **THIS ACTION IS MADE FINAL**. See MPEP § 706.07(a). Applicant is reminded of the extension of time policy as set forth in 37 CFR 1.136(a).

A shortened statutory period for reply to this final action is set to expire THREE MONTHS from the mailing date of this action. In the event a first reply is filed within TWO MONTHS of the mailing date of this final action and the advisory action is not mailed until after the end of the THREE-MONTH shortened statutory period, then the shortened statutory period will expire on the date the advisory action is mailed, and any


Art Unit: 1775

extension fee pursuant to 37 CFR 1.136(a) will be calculated from the mailing date of the advisory action. In no event, however, will the statutory period for reply expire later than SIX MONTHS from the date of this final action.

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Cathy Lam whose telephone number is (571) 272-1538. The examiner can normally be reached on 9am-6pm.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Jennifer McNeil can be reached on (571) 272-1540. The fax phone number for the organization where this application or proceeding is assigned is 571-273-8300.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see <http://pair-direct.uspto.gov>. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).


Cathy Lam
Primary Examiner
Art Unit 1775

cfl
March 02, 2006